

11.(Amended) A method for applying an adhesive to a wafer comprising:

providing a wafer having a surface;

applying an instant setting adhesive composition on the surface of the wafer in a configuration wherein a plurality of portions of the surface have the instant setting adhesive composition dispensed thereon and one or more zones are essentially free of the instant setting adhesive composition, wherein the instant setting adhesive composition has a thixotropic index from about 4 to about 6.

83.(New) A method for applying an adhesive to a wafer comprising:

providing a wafer having a surface; and

applying an instant setting adhesive composition onto a plurality of portions of the surface of the wafer in a configuration, wherein the instant setting adhesive composition becomes non-flowable and substantially maintains the configuration in which the instant setting adhesive composition is applied within about 0.1 seconds to about 120 seconds after the instant setting adhesive is applied to the surface.

84.(New) The method of claim 83 wherein the instant setting adhesive composition becomes non-flowable and substantially maintains the configuration within about 0.1 seconds to about 60 seconds.

85.(New) The method of claim 83 wherein the instant setting adhesive composition becomes non-flowable and substantially maintains the configuration within 0.1 seconds to 120 seconds at a temperature of about 20°C to about 30°C.

86.(New) The method of claim 83 wherein one or more zones of the surface are essentially free of the instant setting adhesive composition, and further wherein the zones comprise singulation streets.

87.(New) The method of claim 83 wherein one or more zones of the surface are essentially free of the instant setting adhesive composition, and further wherein the zones comprise regions having exposed bond pads.

88.(New) The method of claim 83 wherein applying the instant setting adhesive composition to the surface of the wafer comprises a technique selected from the group of screen printing, depositing and patterning, syringe applying, stenciling, dip coating, spraying, dot shooting, and combinations thereof.

89.(New) The method of claim 83 wherein the instant setting adhesive comprises an adhesive component selected from the group of a cyanoacrylate adhesive, an anaerobic acrylic adhesive, and mixtures thereof.

90.(New) The method of claim 14 wherein the instant setting adhesive composition becomes non-flowable and substantially maintains the configuration in which the instant setting adhesive composition was applied within about 0.1 seconds to about 120 seconds after the instant setting adhesive composition is applied to the surface.

91.(New) The method of claim 11 wherein the instant setting adhesive composition becomes non-flowable and substantially maintains the configuration within about 0.1 seconds to about 60 seconds.

92.(New) The method of claim 11 wherein the instant setting adhesive composition becomes non-flowable and substantially maintains the configuration within 0.1 seconds to 120 seconds at a temperature of about 20°C to about 30°C.